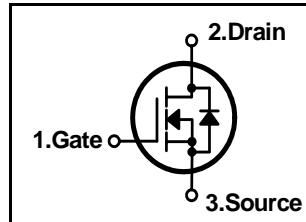


N-Channel MOSFET

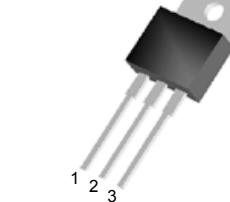
Features

- Low $R_{DS(on)}$ (0.012Ω)@ $V_{GS}=10V$
- Low Gate Charge (Typical 90nC)
- Low C_{rss} (Typical 215pF)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Maximum Junction Temperature Range



$BV_{DSS} = 75V$
 $R_{DS(ON)} = 0.012 \text{ ohm}$
 $I_D = 80A$

TO-220



General Description

This N-channel enhancement mode field-effect power transistor using DI semiconductor's advanced planar stripe, DMOS technology intended for battery operated systems like a DC-DC converter motor control , ups ,audio amplifier.

Also, especially designed to minimize $r_{ds(on)}$, low gate charge and high rugged avalanche characteristics.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{DSS}	Drain to Source Voltage	75	V
I_D	Continuous Drain Current(@ $T_C = 25^\circ\text{C}$)	80	A
	Continuous Drain Current(@ $T_C = 100^\circ\text{C}$)	46	A
I_{DM}	Drain Current Pulsed	(Note 1)	A
V_{GS}	Gate to Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	V/ns
P_D	Total Power Dissipation(@ $T_C = 25^\circ\text{C}$)	176	W
	Derating Factor above 25 °C	1.05	W/°C
T_{STG}, T_J	Operating Junction Temperature & Storage Temperature	- 55 ~ 175	°C
T_L	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.	300	°C

Thermal Characteristics

Symbol	Parameter	Value			Units
		Min.	Typ.	Max.	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	-	-	0.85	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Sink	-	0.5	-	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	-	-	62.5	°C/W

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Electrical Characteristics ($T_C = 25^\circ C$ unless otherwise noted)

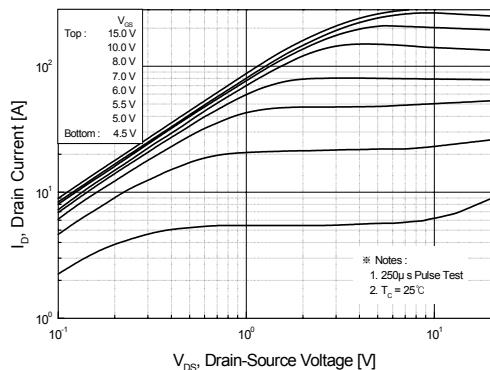
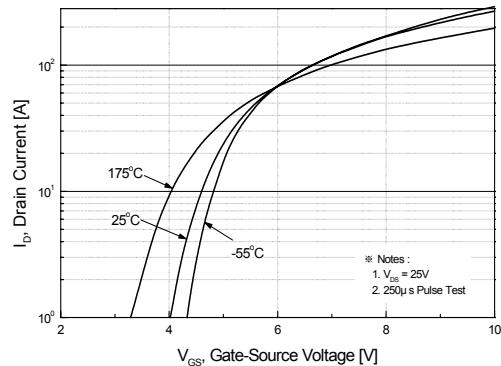
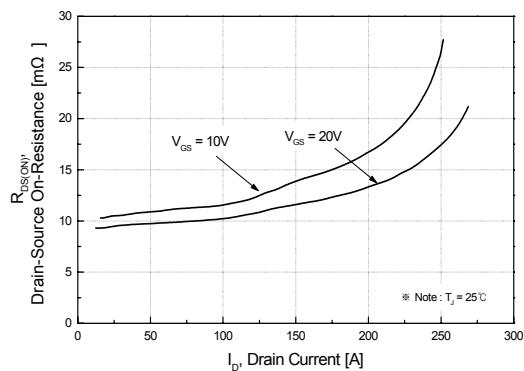
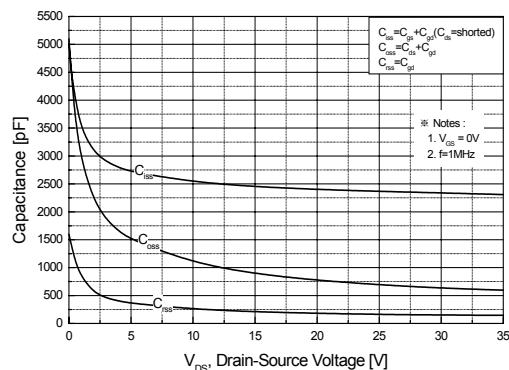
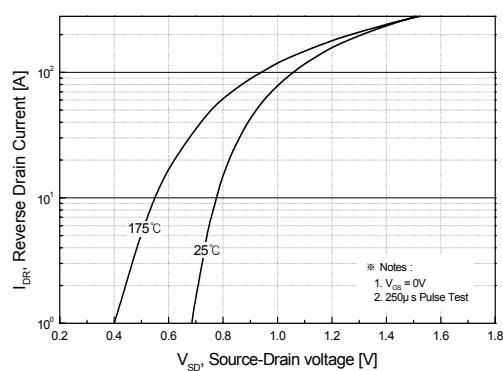
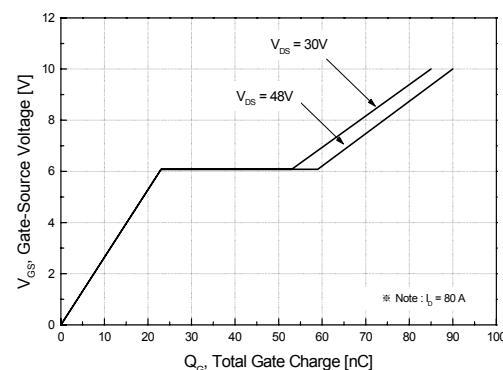
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	75	-	-	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature coefficient	$I_D = 250\mu A$, referenced to $25^\circ C$	-	0.066	-	$V/\text{ }^\circ C$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 75V, V_{GS} = 0V$	-	-	1	μA
		$V_{DS} = 60V, T_C = 150^\circ C$	-	-	10	μA
I_{GSS}	Gate-Source Leakage, Forward	$V_{GS} = 20V, V_{DS} = 0V$			100	nA
	Gate-Source Leakage, Reverse	$V_{GS} = -20V, V_{DS} = 0V$	-	-	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	-	4.0	V
$R_{DS(ON)}$	Static Drain-Source On-state Resistance	$V_{GS} = 10V, I_D = 40A$	-	-	0.012	Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	-	3420	4250	pF
C_{oss}	Output Capacitance		-	1320	1650	
C_{rss}	Reverse Transfer Capacitance		-	215	340	
Dynamic Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 37.5V, I_D = 40A, R_G = 50\Omega$ * see fig. 13. (Note 4, 5)	-	60	120	ns
t_r	Rise Time		-	70	160	
$t_{d(off)}$	Turn-off Delay Time		-	195	310	
t_f	Fall Time		-	120	260	
Q_g	Total Gate Charge	$V_{DS} = 60V, V_{GS} = 10V, I_D = 75A$ * see fig. 12. (Note 4, 5)	-	90	110	nC
Q_{gs}	Gate-Source Charge		-	20	-	
Q_{gd}	Gate-Drain Charge(Miller Charge)		-	33	-	

Source-Drain Diode Ratings and Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit.
I_S	Continuous Source Current	Integral Reverse p-n Junction Diode in the MOSFET	-	-	80	A
I_{SM}	Pulsed Source Current		-	-	320	
V_{SD}	Diode Forward Voltage	$I_S = 80A, V_{GS} = 0V$	-	-	1.5	V
t_{rr}	Reverse Recovery Time	$I_S = 80A, V_{GS} = 0V, dI_F/dt = 100A/us$	-	92	-	ns
Q_{rr}	Reverse Recovery Charge		-	160	-	nC

* NOTES

1. Repetitive rating : pulse width limited by junction temperature
2. $L = 320 \mu H, I_{AS} = 80A, V_{DD} = 25V, R_G = 0\Omega$, Starting $T_J = 25^\circ C$
3. $ISD \leq 80A, di/dt \leq 300A/us, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ C$
4. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
5. Essentially independent of operating temperature.

DFP75N75**Fig 1. On-State Characteristics****Fig 2. Transfer Characteristics****Fig 3. On Resistance Variation vs. Drain Current and Gate Voltage****Fig 5. Capacitance Characteristics****Fig 4. On State Current vs. Allowable Case Temperature****Fig 6. Gate Charge Characteristics**

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Fig 7. Breakdown Voltage Variation vs. Junction Temperature

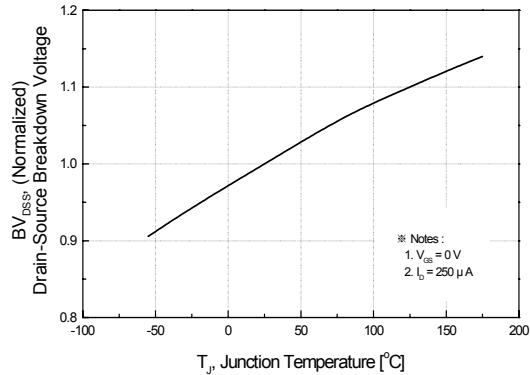


Fig 8. On-Resistance Variation vs. Junction Temperature

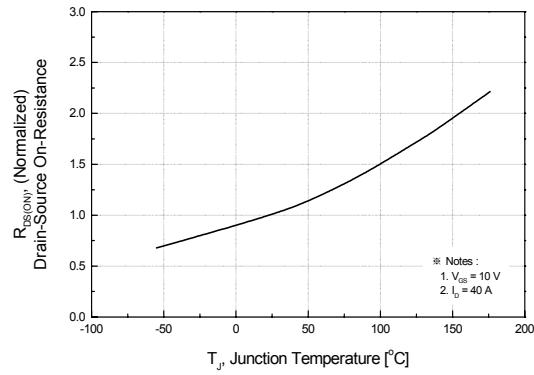


Fig 9. Maximum Safe Operating Area

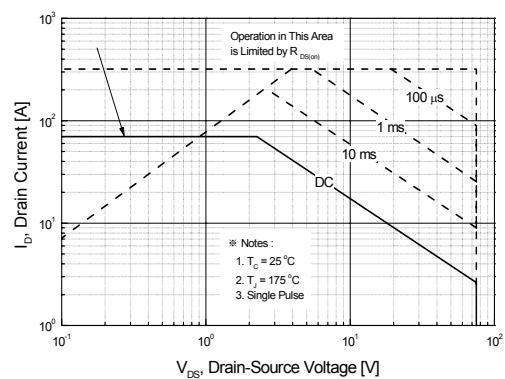


Fig 10. Maximum Drain Current vs. Case Temperature

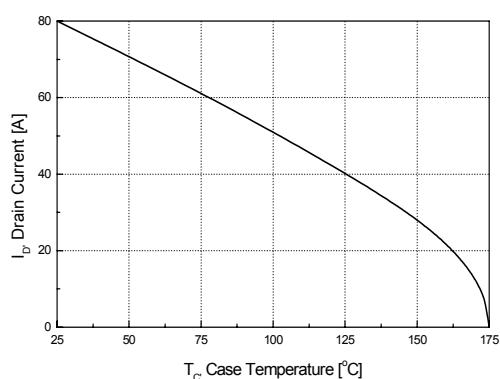
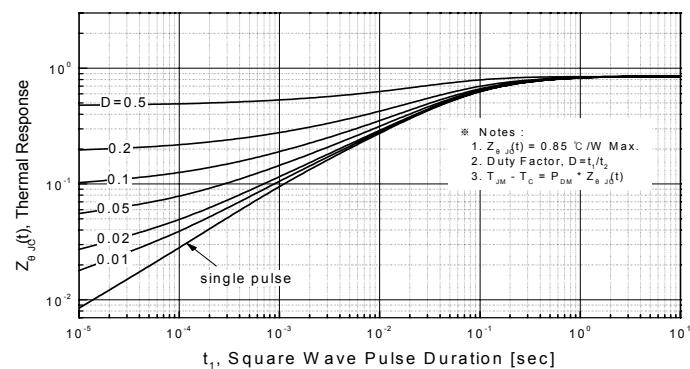


Fig 11. Transient Thermal Response Curve



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Fig. 12. Gate Charge Test Circuit & Waveforms

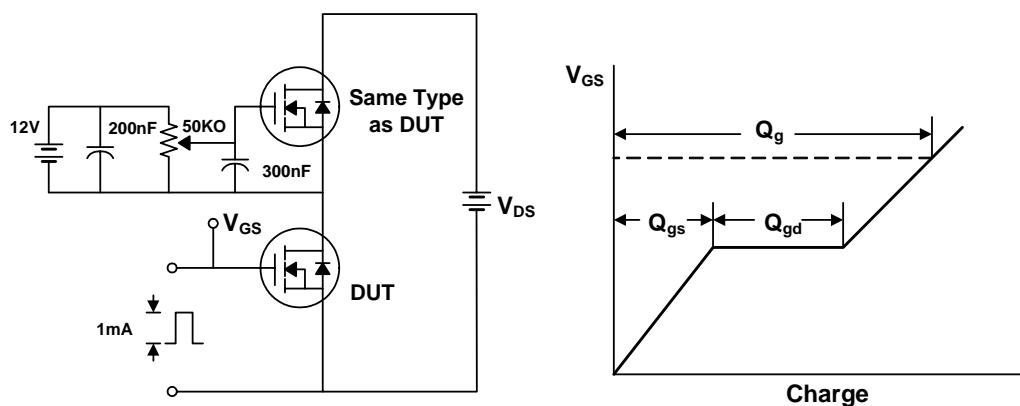


Fig 13. Switching Time Test Circuit & Waveforms

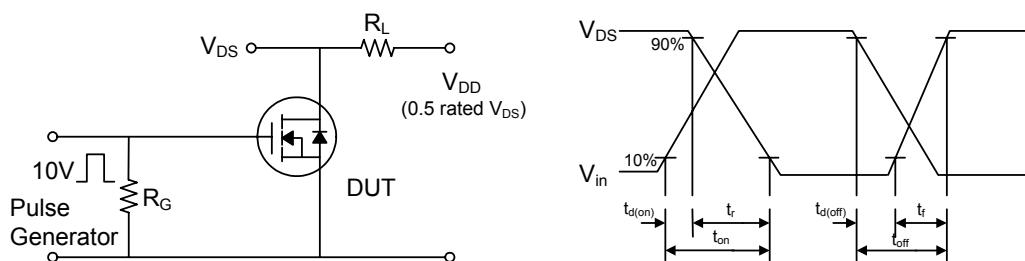
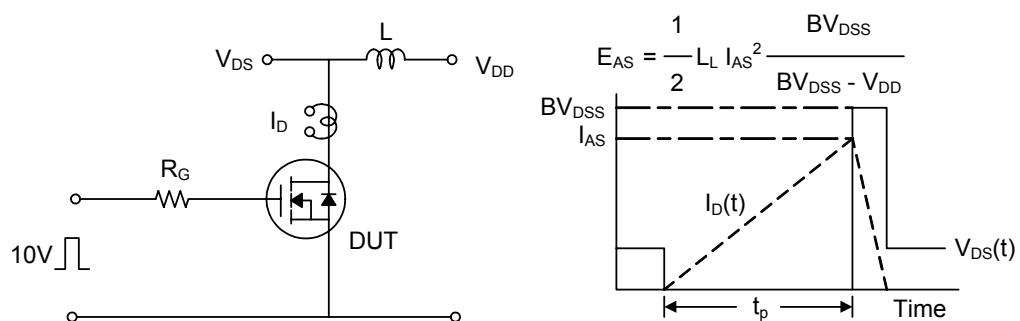
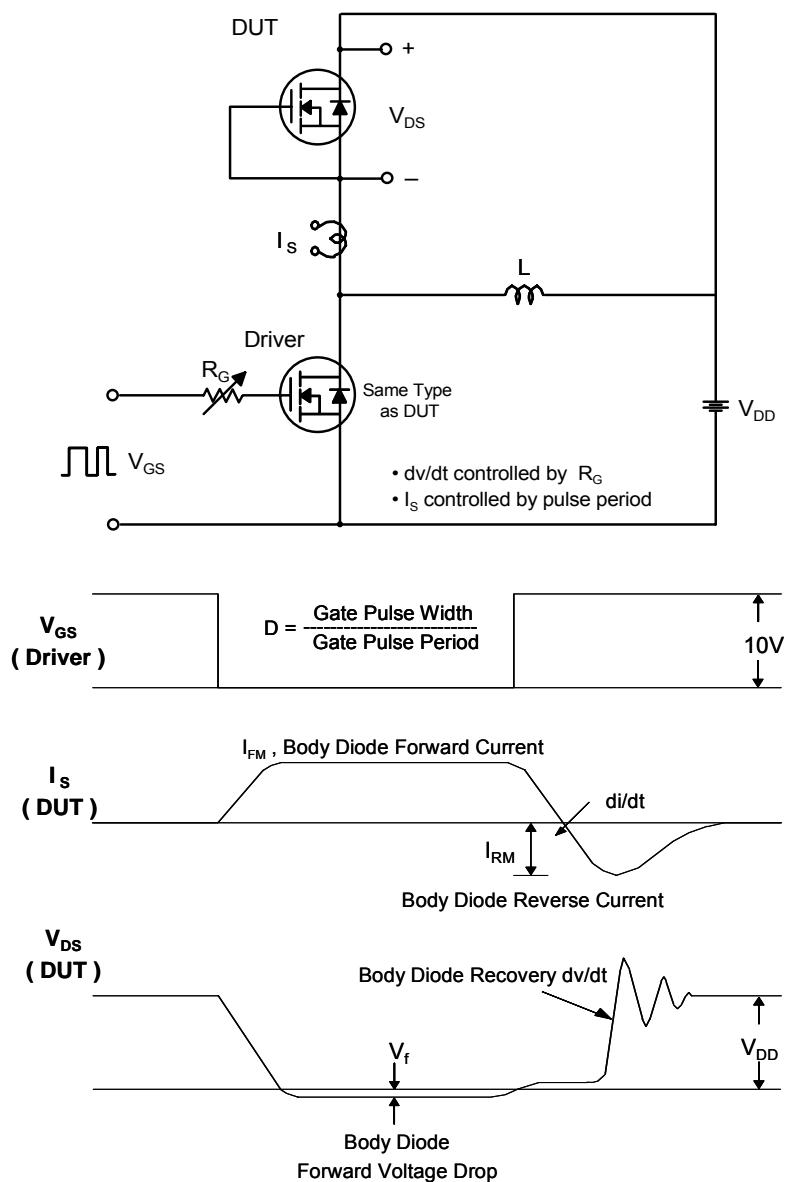


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig. 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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TO-220 Package Dimension

Dim.	mm			Inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.12	6.32	6.52	0.241	0.249	0.257
B	9.00	9.20	9.40	0.354	0.362	0.370
C	12.88	13.08	13.28	0.507	0.515	0.523
D	2.70	2.80	2.90	0.106	0.110	0.114
E	1.20	1.30	1.40	0.047	0.051	0.055
F	15.12	15.52	15.92	0.595	0.611	0.627
G	2.70	3.00	3.30	0.106	0.118	0.130
H	4.30	4.50	4.70	0.169	0.177	0.185
I	1.25	1.30	1.40	0.049	0.051	0.055
J	0.45	0.50	0.60	0.018	0.020	0.024
K	2.30	2.40	2.50	0.091	0.094	0.098
L		9.90			0.390	
M	1.42	1.52	1.62	0.056	0.060	0.064
N	0.75	0.85	0.95	0.030	0.03	0.037
O	2.44	2.54	2.64	0.096	0.100	0.104
P	4.88	5.08	5.28	0.192	0.200	0.208
ϕ		3.60			0.142	

